ESS503 GID-5-EV03.3.2

ESS503 Ceramic Piezo-Resistive Pressure & Temperature Sensor Cell

**MONOLITHIC THCIK-FILM | AI2O3 96%** 



Range: 0~2bar~100bar/600bar
Size:18mm\*6.35mm; 18mm\*3.5mm
Diaphragm Material: Ceramic Al2O3 96%
Power Supply:
2-30V
Long Term Stability: 0.3%/FS
NTC Thermistor
Working Temperature: -40...+135 °C

## Description

ESS503 Monolithic Pressure & Temperature Sensor Cell are made with a Ceramic Base Plate and Diaphragm and work following the piezoresistive principle. With temperature sensor mounted, ESS503 can detect temperature change via NTC Thermistor.

By integrating an **NTC thermistor**, ESS503 can continuously monitor the temperature and apply real-time compensation to the pressure readings, and can provide the necessary temperature data, allowing a more comprehensive understanding of the environment.

The Wheatstone bridge is **Screen Printed** on one side of the flush ceramic diaphragm which is, in turn, glued to the sensor's body. The bridge faces the inside where a cavity is made and the diaphragm's opposite side can therefore be exposed directly to the medium to be measured.

As the same as ESS501 and ESS502, ESS503 is also available with two kinds size: **18\*6.35mm and 18\*3.5mm** (thin type).

## Key Features & Benefits

- Pressure range 0-2bar-100bar/600bar
- Excellent resistance to corrosion and abrasion
- Integrated with NTC Thermistor
- Thermally compensated
- Extended customization
- Extended choice of measuring ranges

### Application

- Cooling equipment & A/C system
- Automotive and vehicle
- Industrial process control
- HVAC system
- Refrigeration equipment
- Air conditioning unit

#### **Technical Characteristics**

Parameter	Unit	Description
Sensor type	-	absolute (A), gauge (R) or sealed gauge (S)
Technology	-	Piezoresistive (Ceramic Thick Film)
Diaphragm material	-	Ceramic Al <sub>2</sub> O <sub>3</sub> 96% (standard), 99.6% or sapphire (on request)
Weight	g	≤ 8 (ceramic cell only)
Response time	ms	≤1



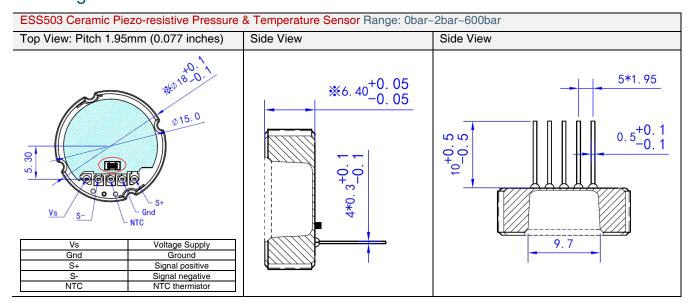


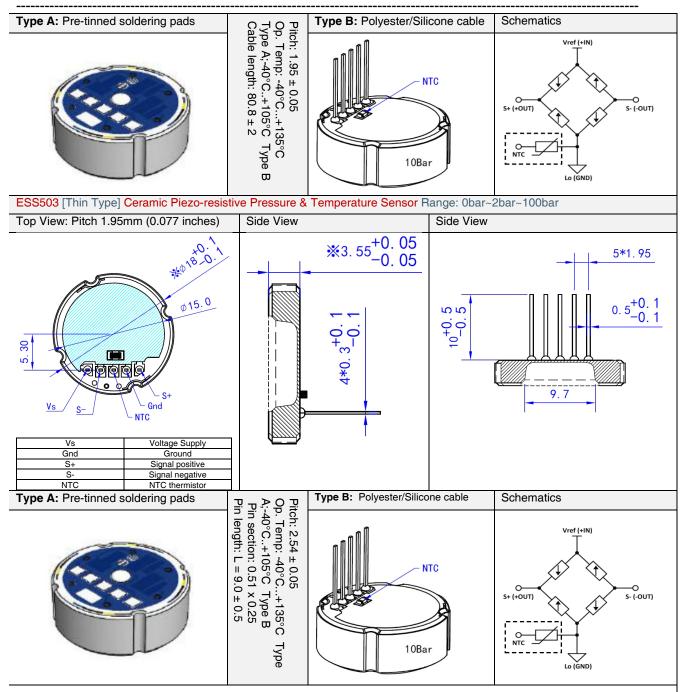
Supply voltage		VDC	230										
Offset		mv/v	2 ±4 (Other nominal values available on request)										
Current		mA		≤ 1.3 @ 10V									
TCR				≤100ppm/℃@-40℃~120℃									
NTC			10kΩ±1.5%@25°C, B=3950K										
Operating temperature		°C	-40+135 (-40 °F+275 °F)										
Storage temperature		°C	-40+150 (-40 °F+302 °F)										
Impedance		kΩ	11 ± 30%										
Nominal	bar	0.5 <b>*</b>	1*	2	5	10	20	50	100	200	400	600	800 *
pressure FSO	psi	7	14	29	73	145	290	725	1450	2900	5800	8700	11600
Overload	bar	1	2	4	10	15	35	100	150	350	500	750	1000
pressure	psi	14	29	58	145	217	507	1450	2175	5075	7250	10875	14500
Burst pressure	bar	2	3	6	15	25	65	120	200	500	650	950	1250
	psi	29	43	87	217	362	942	1740	2900	7250	9425	13775	18125
Vacuum capability	bar	-0.1	-0.5	-0.5	-1	-1	-1	-1	-1	-1	-1	-1	-1
	psi	-1.4	-7	-7	-14	-14	-14	-14	-14	-14	-14	-14	-14
Туре	-	R	A/R/S	A/R/S	A/R/S	A/R/S	A/R/S	A/R/S	S	S	S	S	S
Total thickness	mm/in	6.40±0.05/2.51±0.2											
	mm/in		$3.55 \pm 0.05 / 1.40 \pm 0.2$ ; for thin type										
Sensitivity	mv/v	1.4-	2.0-3.6	2.3-3.5	2.3-4.0	3.1-5.5	2.4-4.0	4.0-6.0	3.0-4.8	2.5-3.9	3.1-4.8	3.1-4.8	2.0-3.5
Accuracy	%/fs	0.4/0	0.3/0.9	0.3/0.6	0.2/0.4	0.2/0.5	0.2/0.5	0.2/0.5	0.2/0.5	0.4/0.9	0.5/1.0	0.5/1.0	0.5/1.0
Thermal offset shift(typ./max.)	%/fs/k	± 0.0	± 0.005 / ± 0.040 25 °C85 °C (77 °F185 °F)										
Thermal span shift	%/fs/k	≤±0 ≤±0 ≤±0	.012	_		0 °C70 °C (32 °F158 °F) -25 °C0 °C / 70 °C85 °C (-13 °F32 °F / 158 °F185 °F) -40 °C25 °C / 85 °C135 °C (-40 °F13 °F / 185 °F275 °F)							
Reliability tests	-		hours @8!	,	,	1	500 thermal shocks -40°C+150 °C (-40 °F +302 °F) 10 million 0 bar to Pnom pressure cycles						

 $Tests\ performed\ at\ 25^{\circ}C\ in\ Eastsensor\ housings, unless\ otherwise\ specified.\ Different\ housings\ may\ affect\ performances.$ 

- 1. Psi values for reference only. 2. The sensitivity of each production batch is constant, within the indicated range and with minimal dispersion.
- $\textbf{3.} \textit{Accuracy} = \sqrt{\textit{NonLinearity}^2 + \textit{Hysteresis}^2 + \textit{NonRepeatability}^2}, \textit{terminal based}.$
- 4. All technical characteristics will remain within indicated ranges performing the above-mentioned reliability tests. 5. Please consult manufacturer when pressure range with \*\*

# **Drawing**





- 1. Storage Conditions: Store at 10~35°C with ≤ 70% RH. Avoid places that are too hot, exposed to direct sunlight, dusty, or have corrosive gases. The metal pins can easily oxidize in the air, so it's recommended to use the product within 10 days after unpacking. Under proper storage conditions, the soldering validity is 12 months. If stored for more than 12 months, the ceramic core needs to be rechecked for solderability and can only be used if it passes inspection.
- 2. Product Installation Pressure: During crimping installation, the crimping pressure should not exceed 20KN, and the direct pressure on the core should not exceed 5KN. Excessive force may damage the core structure or cause abnormal output signals. The ceramic core should not come into direct contact with hard objects like a metal casing to avoid significant internal stress and unstable output.
- 3. Sealing Recommendations: When using sealing rings, ensure that the sealing ring is centered with the elastic diaphragm and without uneven force. The inner diameter of the sealing ring should be > 11.0mm and the outer diameter < 16.0mm after compression deformation.
- 4. Solder Pads: The pressure core PIN is constructed of nickel-tin copper. The welding hole for the PIN measures 0.7mm, with a pad width exceeding 0.5mm. The soldering temperature must not exceed 370 °C, with each soldering session limited to under 3 seconds and a maximum of 3 sessions.



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# **Ordering Procedure**

ESS5			iezores		ressu	re Se	nsor						
	Cod	le	Model										
	01		Pressure Sensor Cell, Monolithic 18*6.35mm										
	01 T		Pressure Sensor Cell, Monolithic 18*3.35mm  Pressure Sensor Module, Monolithic (with pcb) 4-20mA; Electronics on PCB										
	01-1												
	01-\									Electronics on PCB			
	01-11		Pressure Sensor Module, Monolithic (with pcb) I2C Output; Electronics on PCB										
	02 (	- /	Pressure Sensor Cell, Flush diaphragm 18*6.35mm  Pressure Sensor Cell, Flush diaphragm 18*3.35mm										
		8)Thin											
	02 (	/	Pressure Sensor Cell, Flush diaphragm 12*12*3mm  Pressure Sensor Cell, Flush diaphragm 14*14*3mm  Pressure Sensor Cell, Flush diaphragm 21*4.35mm  Pressure Sensor Module, Flush diaphragm (with pcb) 4-20mA; Electronics on PCB										
	02 (	/											
	02 (2	21)											
	02-I												
	02-10		Pressure Sensor Module, Flush diaphragm (with pcb) 4-20mA; Electronics on Ceramic										
	02-\		Pressure Sensor Module, Flush diaphragm (with pcb) 0.5-4.5V; Electronics on PCB Pressure Sensor Module, Flush diaphragm (with pcb) 0.5-4.5V; Electronics on Ceramic Pressure Sensor Module, Flush diaphragm (with pcb) I2C Output; Electronics on PCB										
	02-\												
	02-11	IC											
	02-1	ICOC	Pressi	ure Sen	sor N	lodule	e, Flush di	iaphragm (	with pcb) I20	C Output; Electronics on Ceramic			
	03		Pressi	ure Sen	sor C	ell (w	ith tempe	rature sens	sor mounted	), Monolithic 18*6.35mm			
	03 7	Thin	Pressi	Pressure Sensor Cell (with temperature sensor mounted), Monolithic 18*3.35mm									
			Code	Span				Code					
			R01	00.5	5 bar	[07	'psi]	R07	050 bar	[0720psi]			
	ŀ	ĺ	R02	01 k		[01		R08	0100 bar	[01450psi]			
	ŀ		R03	02 k	oar	[029psi] [072psi]		R09	0200 bar	[02900psi]			
	ŀ	ĺ	R04	05 k	oar			R10 R11	0400 bar [05800psi] 0600 bar [08700psi]				
	ŀ		R05	010									
	ŀ		R06	020	bar	_	290psi]	R12	0800 bar	[011600psi]			
	ŀ			Code	Pi		re Type						
	ŀ			R		auge							
	ŀ			Α		osolu							
				S			Gauge						
	ŀ			1	C	ode	Sensitivity adjustment						
					0		Without	, ,					
					9		On requ	est					
							Code	Therma	l offset				
							0			ermally compensated)			
							1	≤±0.06 % FS/K (not thermally compensated) ≤±0.04 % FS/K					
							2	≤±0.04 % F5/K ≤±0.02 % FS/K					
								Code Termination type					
								02					
			02 4 pins, Pre-tinned pads, pitch 1.95 mm 03 4 pins, Silicone single wires 80 mm, pitc										
I								03	Code				
	l								1	Additional coating Without			
	l l												
									2	Parylene coating			

Note: 1 Extremely attention must be paid to sensor installation process to avoid any miss conduction that affect the sensor performance, 2 please protect the diaphragm and the compensated board carefully to prevent any damage. 3 Please contact us if your requested working temperature lower than -20 °C;